

PCN Number:	20231128001.2		PCN Date:	November 29, 2023						
Title:	Adding TI-Chengdu (CD-PR) as additional wafer probe test site									
Customer Contact:	Change Management team	Dept:	Quality Services							
Proposed 1st Ship Date:	May 27, 2024	Estimated Sample Availability:	Samples not supported							
Change Type:										
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design	<input type="checkbox"/>	Wafer Bump Site					
<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet	<input type="checkbox"/>	Wafer Bump Material					
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change	<input type="checkbox"/>	Wafer Bump Process					
<input type="checkbox"/>	Mechanical Specification	<input checked="" type="checkbox"/>	Test Site	<input type="checkbox"/>	Wafer Fab Site					
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input type="checkbox"/>	Wafer Fab Materials					
		<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Process					
PCN Details										
Description of Change:										
Texas Instruments Incorporated has qualified TI-Chengdu (CD-PR) as additional wafer probe test site for the devices listed below to support high volume ramps.										
<table border="1" style="margin-left: auto; margin-right: auto;"> <tr> <td style="text-align: center;">Current:</td> <td style="text-align: center;">New:</td> </tr> <tr> <td style="text-align: center;">Probe Site (EWS)</td> <td style="text-align: center;"> <table border="1" style="display: inline-table;"> <tr> <td style="text-align: center;"><i>TI Clark (CLARK-PR)</i></td> <td style="text-align: center;"><i>TI Chengdu (CD-PR)</i></td> </tr> </table> </td> </tr> </table>					Current:	New:	Probe Site (EWS)	<table border="1" style="display: inline-table;"> <tr> <td style="text-align: center;"><i>TI Clark (CLARK-PR)</i></td> <td style="text-align: center;"><i>TI Chengdu (CD-PR)</i></td> </tr> </table>	<i>TI Clark (CLARK-PR)</i>	<i>TI Chengdu (CD-PR)</i>
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Test coverage, insertions, conditions will remain consistent with current testing.										
Reason for Change:										
Supply Continuity										
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):										
None.										
Changes to product identification resulting from this PCN:										
None.										
Product Affected:										
AWR1243FBIGABLQ1	AWR1443FQIGABLQ1	AWR2243ABGABLRQ1	AWR2243AVBGABLRQ1							
AWR1243FBIGABLRQ1	AWR1443FQIGABLRQ1	AWR2243APBGABLQ1	XA1443FQGABL							
AWR1243FVBIGABLRQ1	AWR2243ABGABLQ1	AWR2243APBGABLRQ1	XA2243ABGABL							

ZVEI ID: SEM-TF-01

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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